

NLAST4053

Analog Multiplexer/ Demultiplexer

TTL Compatible, Triple 2:1 Analog Switch–Multiplexer Improved Process, Sub–Micron Silicon Gate CMOS

The NLAST4053 is an improved version of the MC14053 and MC74HC4053 fabricated in sub-micron Silicon Gate CMOS technology for lower $R_{DS(on)}$ resistance and improved linearity with low current. This device may be operated either with a single supply or dual supply up to ± 3 V to pass a 6 V_{PP} signal without coupling capacitors.

When operating in single supply mode, it is only necessary to tie V_{EE}, pin 7 to ground. For dual supply operation, V_{EE} is tied to a negative voltage, not to exceed maximum ratings. Translation is provided in the device, the Address and Inhibit pins are standard TTL level compatible. For CMOS compatibility see NLAS4053. Pin for pin compatible with all industry standard versions of '4053.'

- Improved $R_{DS(on)}$ Specifications
- Pin for Pin Replacement for MAX4053 and MAX4053A
 - One Half the Resistance Operating at 5.0 Volts
- Single or Dual Supply Operation
 - Single 3–5 Volt Operation, or Dual ± 3 Volt Operation
 - With V_{CC} of 3.0 to 3.3 V, Device Can Interface with 1.8 V Logic, No Translators Needed
 - Address and Inhibit Pins are Over–Voltage Tolerant and May Be Driven Up +6 V Regardless of V_{CC}
- Address and Inhibit Pins are Standard TTL Compatible
 - Greatly Improved Noise Margin Over MAX4053 and MAX4053A
 - True TTL Compatibility V_{IL} = 0.8 V, V_{IH} = 2.0 V
- Improved Linearity Over Standard HC4053 Devices
- Popular SOIC, and Space Saving TSSOP, and QSOP 16 Pin Packages
- This is a Pb–Free Device



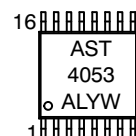
ON Semiconductor®

<http://onsemi.com>

MARKING DIAGRAM



TSSOP-16
DT SUFFIX
CASE 948F



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week

ORDERING INFORMATION

Device	Package	Shipping†
NLAST4053DTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NLAST4053



Figure 1. Pin Connection
(Top View)

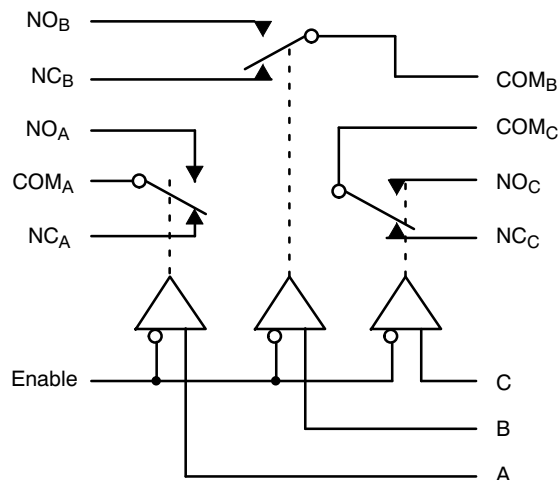


Figure 2. Logic Diagram

TRUTH TABLE

Inhibit	Address			ON SWITCHES*
	C	B	A	
1	X don't care	X don't care	X don't care	All switches open
0	0	0	0	COM _A -NC _A , COM _B -NC _B , COM _C -NC _C
0	0	0	1	COM _A -NO _A , COM _B -NC _B , COM _C -NC _C
0	0	1	0	COM _A -NC _A , COM _B -NO _B , COM _C -NC _C
0	0	1	1	COM _A -NO _A , COM _B -NO _B , COM _C -NC _C
0	1	0	0	COM _A -NC _A , COM _B -NC _B , COM _C -NO _C
0	1	0	1	COM _A -NO _A , COM _B -NC _B , COM _C -NO _C
0	1	1	0	COM _A -NC _A , COM _B -NO _B , COM _C -NO _C
0	1	1	1	COM _A -NO _A , COM _B -NO _B , COM _C -NO _C

*NO, NC, and COM pins are identical and interchangeable. Either may be considered an input or output; signals pass equally well in either direction.

NLAST4053

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{EE}	Negative DC Supply Voltage (Referenced to GND)	-7.0 to +0.5	V
V _{CC}	Positive DC Supply Voltage (Note 1) (Referenced to GND) (Referenced to V _{EE})	-0.5 to +7.0 -0.5 to +7.0	V
V _{IS}	Analog Input Voltage	V _{EE} -0.5 to V _{CC} +0.5	V
V _{IN}	Digital Input Voltage (Referenced to GND)	-0.5 to 7.0	V
I	DC Current, Into or Out of Any Pin	± 50	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction Temperature under Bias	+ 150	°C
θ _{JA}	Thermal Resistance SOIC TSSOP QSOP	143 164 164	°C/W
P _D	Power Dissipation in Still Air, SOIC TSSOP QSOP	500 450 450	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 30% - 35%	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 > 1000	V
I _{LATCH-UP}	Latch-Up Performance Above V _{CC} and Below GND at 125°C (Note 5)	± 300	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The absolute value of V_{CC} ± |V_{EE}| ≤ 7.0.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{EE}	Negative DC Supply Voltage (Referenced to GND)	-5.5	GND	V
V _{CC}	Positive DC Supply Voltage (Referenced to GND) (Referenced to V _{EE})	2.5 2.5	5.5 6.6	V
V _{IS}	Analog Input Voltage	V _{EE}	V _{CC}	V
V _{IN}	Digital Input Voltage (Note 6) (Referenced to GND)	0	5.5	V
T _A	Operating Temperature Range, All Package Types	-55	125	°C
t _r , t _f	Input Rise/Fall Time (Channel Select or Enable Inputs) V _{CC} = 3.0 V ± 0.3 V V _{CC} = 5.0 V ± 0.5 V	0 0	100 20	ns/V

6. Unused digital inputs may not be left open. All digital inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

NLAST4053

DC CHARACTERISTICS – Digital Section (Voltages Referenced to GND)

Symbol	Parameter	Condition	V _{CC} V	Guaranteed Limit			Unit
				-55 to 25°C	≤ 85°C	≤ 125°C	
V _{IH}	Minimum High-Level Input Voltage, Address and Inhibit Inputs		3.0	1.6	1.6	1.6	V
			4.5	2.0	2.0	2.0	
			5.5	2.0	2.0	2.0	
V _{IL}	Maximum Low-Level Input Voltage, Address and Inhibit Inputs		3.0	0.5	0.5	0.5	V
			4.5	0.8	0.8	0.8	
			5.5	0.8	0.8	0.8	
I _{IN}	Maximum Input Leakage Current, Address and Inhibit Inputs	V _{IN} = 6.0 or GND	0 V to 6.0 V	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	Address and Inhibit, and V _{IS} = V _{CC} or GND	6.0	4.0	40	80	μA

DC ELECTRICAL CHARACTERISTICS – Analog Section

Symbol	Parameter	Test Conditions	V _{CC} V	V _{EE} V	Guaranteed Limit			Unit
					-55 to 25°C	≤ 85°C	≤ 125°C	
R _{ON}	Maximum "ON" Resistance	V _{IN} = V _{IL} or V _{IH} , V _{IS} = V _{EE} to V _{CC} I _S = 10 mA (Figures 4 thru 9)	3.0	0	86	108	120	Ω
			4.5	0	37	46	55	
			3.0	-3.0	26	33	37	
ΔR _{ON}	Maximum Difference in "ON" Resistance Between Any Two Channels in the Same Package	V _{IN} = V _{IL} or V _{IH} , I _S = 10 mA, V _{IS} = 2.0 V V _{IS} = 3.0 V V _{IS} = 2.0 V	3.0	0	15	20	20	Ω
			4.5	0	2.0	2.0	2.0	
			3.0	-3.0	10	15	15	
R _{flat(ON)}	COM-NO On-Resistance Flatness	V _{com} = 1, 2, 3.5 V V _{com} = -2, 0, 2 V	4.5 3.0	0 -3.0	24 2.0	24 2.0	35 3.0	Ω
I _{NC(OFF)} I _{NO(OFF)}	Maximum Off-Channel Leakage Current	Switch Off V _{IN} = V _{IL} or V _{IH} V _{IO} = V _{CC} -1.0 V or V _{EE} +1.0 V (Figure 17)	6.0	0	0.1	5.0	100	nA
			3.0	-3.0	0.1	5.0	100	
I _{COM(ON)}	Maximum On-Channel Leakage Current, Channel-to-Channel	Switch On V _{IO} = V _{CC} -1.0 V or V _{EE} +1.0 V (Figure 17)	6.0	0	0.1	5.0	100	nA
			3.0	-3.0	0.1	5.0	100	

NLAST4053

AC CHARACTERISTICS (Input $t_r = t_f = 3$ ns)

Symbol	Parameter	Test Conditions	V _{CC} V	V _{EE} V	Guaranteed Limit				Unit
					-55 to 25°C		≤ 85°C	≤ 125°C	
					Min	Typ*			
t _{BBM}	Minimum Break-Before-Make Time	V _{IN} = V _{IL} or V _{IH} V _{IS} = V _{CC} R _L = 300 Ω, C _L = 35 pF (Figure 19)	3.0	0.0	1.0	6.5	-	-	ns
			4.5	0.0	1.0	5.0	-	-	
			3.0	-3.0	1.0	3.5	-	-	

*Typical Characteristics are at 25°C.

AC CHARACTERISTICS (C_L = 50 pF, Input $t_r = t_f = 3$ ns)

Symbol	Parameter	V _{CC} V	V _{EE} V	Guaranteed Limit						Unit	
				-55 to 25°C			≤ 85°C		≤ 125°C		
				Min	Typ	Max	Min	Max	Min		Max
t _{TRANS}	Transition Time (Address Selection Time) (Figure 18)	2.5	0			40		45		50	ns
		3.0	0			28		30		35	
		4.5	0			23		25		30	
		3.0	-3.0			23		25		28	
t _{ON}	Turn-on Time (Figures 14, 15, 20, and 21) Enable to N _O or N _C	2.5	0			40		45		50	ns
		3.0	0			28		30		35	
		4.5	0			23		25		30	
		3.0	-3.0			23		25		28	
t _{OFF}	Turn-off Time (Figures 14, 15, 20, and 21) Enable to N _O or N _C	2.5	0			40		45		50	ns
		3.0	0			28		30		35	
		4.5	0			23		25		30	
		3.0	-3.0			23		25		28	

		Typical @ 25°C, V _{CC} = 5.0 V	
C _{IN}	Maximum Input Capacitance, Select Inputs	8	
C _{NO} or C _{NC}	Analog I/O	10	
C _{COM}	Common I/O	10	
C _(ON)	Feedthrough	1.0	

NLAST4053

ADDITIONAL APPLICATION CHARACTERISTICS (GND = 0 V)

Symbol	Parameter	Condition	V _{CC} V	V _{EE} V	Typ	Unit
					25°C	
BW	Maximum On-Channel Bandwidth or Minimum Frequency Response	V _{IS} = ½ (V _{CC} - V _{EE}) Source Amplitude = 0 dBm (Figures 10 and 22)	3.0	0.0	145	MHz
			4.5	0.0	165	
			6.0	0.0	180	
			3.0	-3.0	180	
V _{ISO}	Off-Channel Feedthrough Isolation	f = 100 kHz; V _{IS} = ½ (V _{CC} - V _{EE}) Source = 0 dBm (Figures 12 and 22)	3.0	0.0	-93	dB
			4.5	0.0	-93	
			6.0	0.0	-93	
			3.0	-3.0	-93	
V _{ONL}	Maximum Feedthrough On Loss	V _{IS} = ½ (V _{CC} - V _{EE}) Source = 0 dBm (Figures 10 and 22)	3.0	0.0	-2	dB
			4.5	0.0	-2	
			6.0	0.0	-2	
			3.0	-3.0	-2	
Q	Charge Injection	V _{IN} = V _{CC} to V _{EE} , f _{IS} = 1 kHz, t _r = t _f = 3 ns R _{IS} = 0 Ω, C _L = 1000 pF, Q = C _L * ΔV _{OUT} (Figures 16 and 23)	5.0	0.0	9.0	pC
			3.0	-3.0	12	
THD	Total Harmonic Distortion THD + Noise	f _{IS} = 1 MHz, R _L = 10 KΩ, C _L = 50 pF, V _{IS} = 5.0 V _{PP} sine wave V _{IS} = 6.0 V _{PP} sine wave (Figure 13)	6.0	0.0	0.10	%
			3.0	-3.0	0.05	

NLAST4053

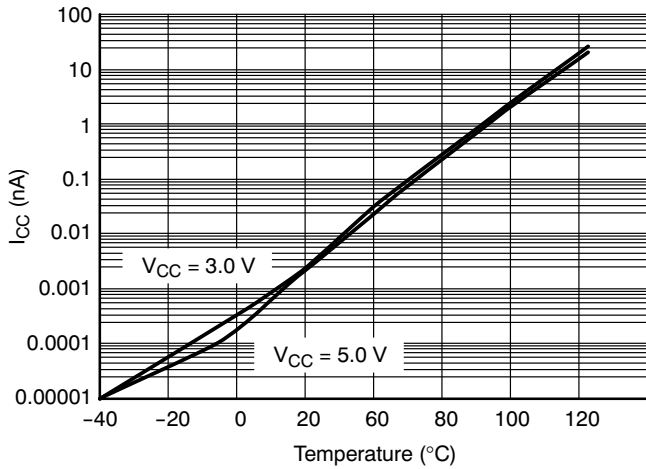


Figure 3. I_{CC} versus Temp, $V_{CC} = 3\text{ V}$ and 5 V

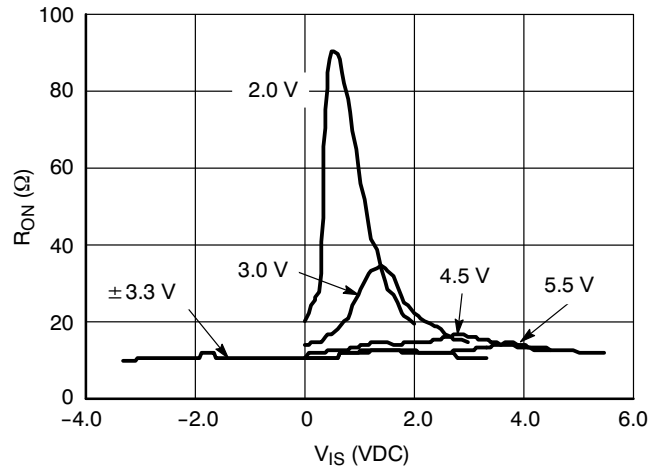


Figure 4. R_{ON} versus V_{CC} , Temp = 25°C

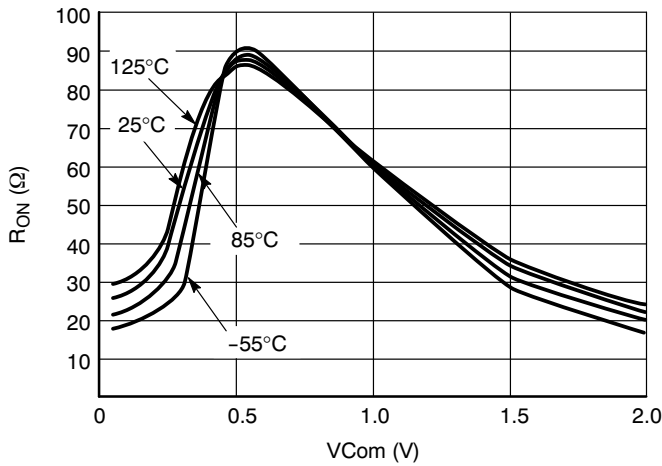


Figure 5. Typical On Resistance
 $V_{CC} = 2.0\text{ V}$, $V_{EE} = 0\text{ V}$

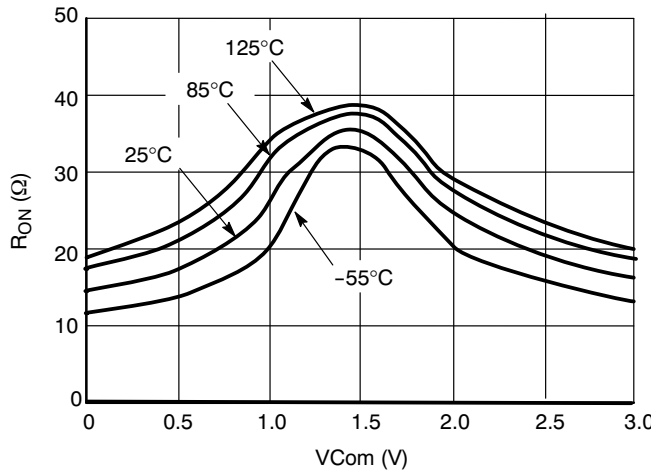


Figure 6. Typical On Resistance
 $V_{CC} = 3.0\text{ V}$, $V_{EE} = 0\text{ V}$

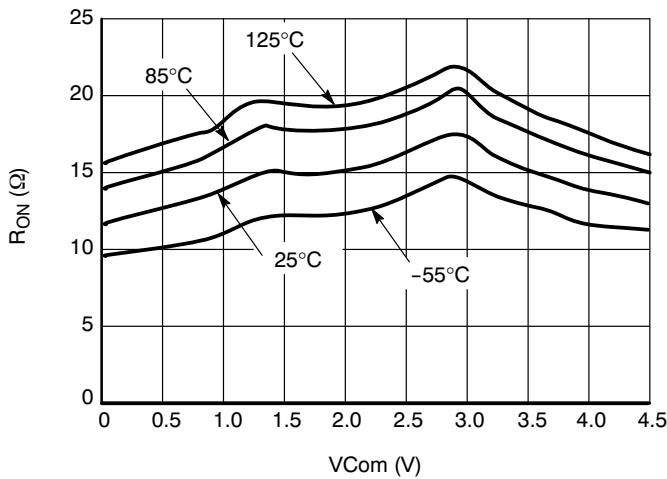


Figure 7. Typical On Resistance
 $V_{CC} = 4.5\text{ V}$, $V_{EE} = 0\text{ V}$

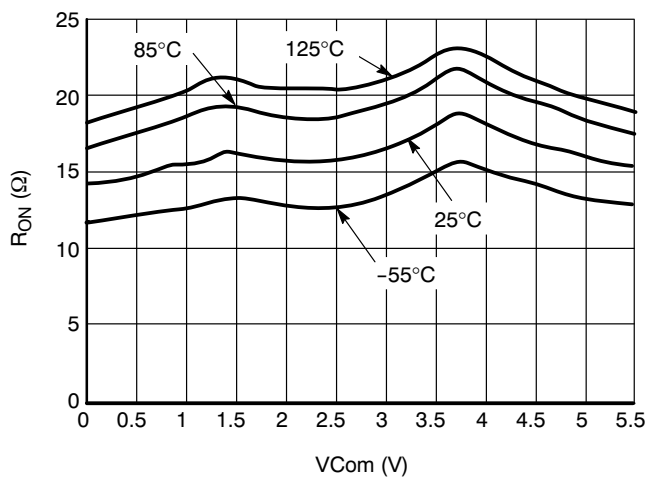


Figure 8. Typical On Resistance
 $V_{CC} = 5.5\text{ V}$, $V_{EE} = 0\text{ V}$

NLAST4053

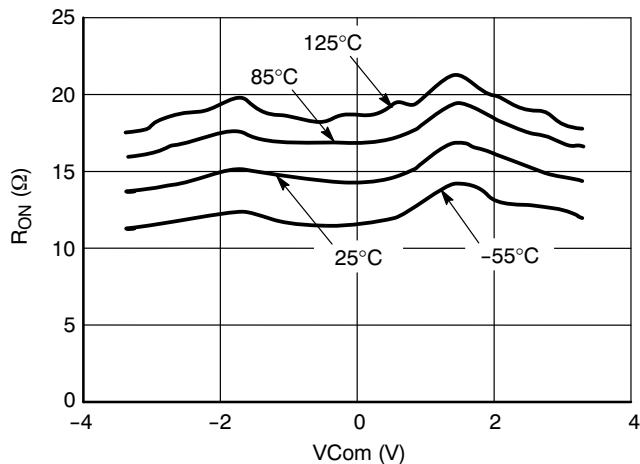


Figure 9. Typical On Resistance
 $V_{CC} = 3.0\text{ V}, V_{EE} = -3.0\text{ V}$

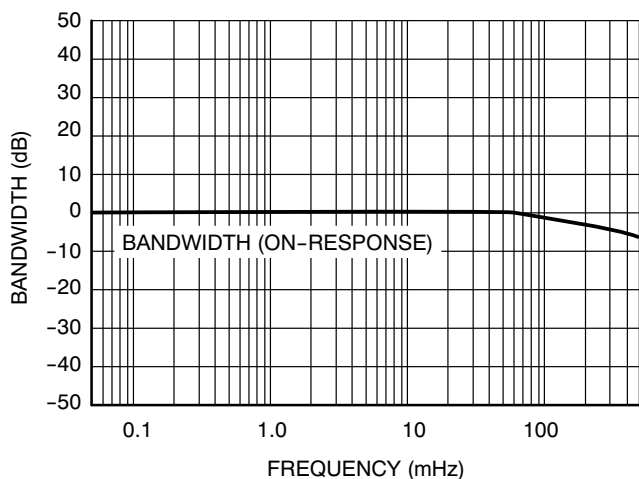


Figure 10. Bandwidth

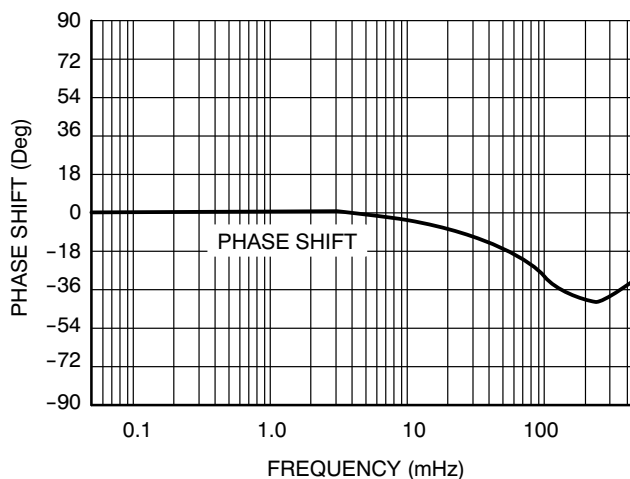


Figure 11. Phase Shift

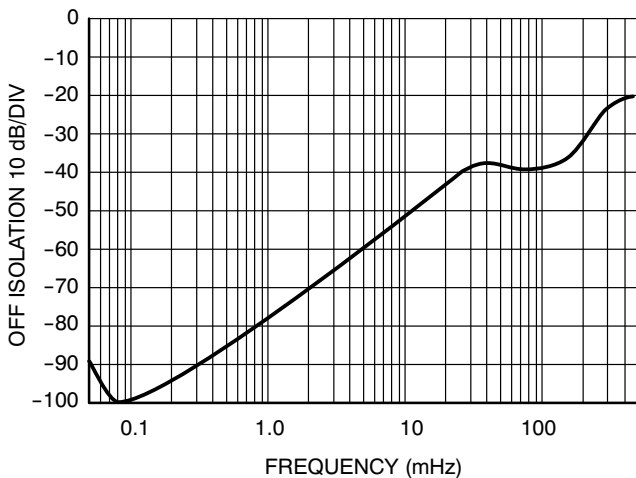


Figure 12. Off Isolation

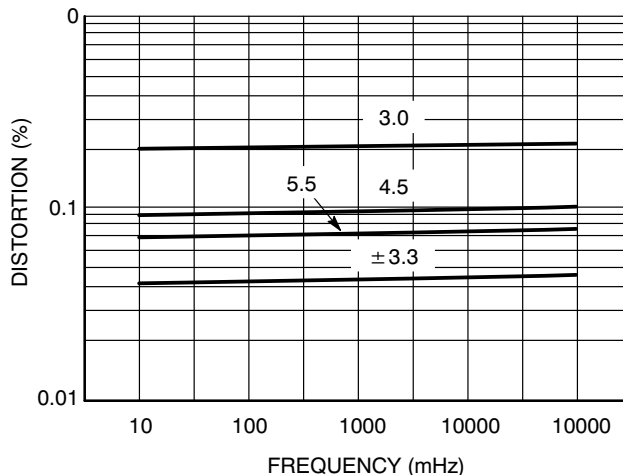


Figure 13. Total Harmonic Distortion

NLAST4053

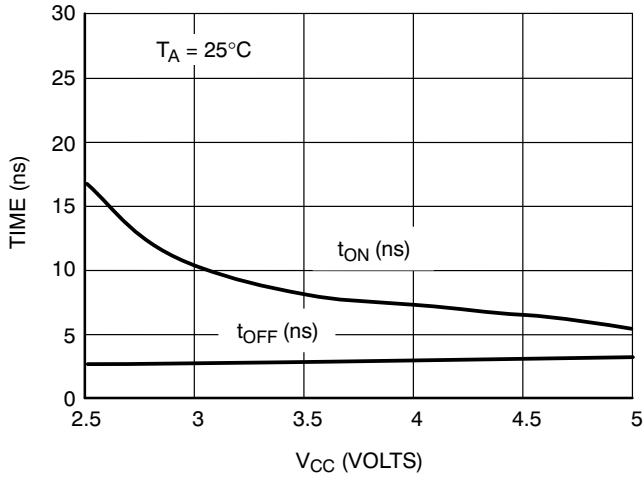


Figure 14. t_{ON} and t_{OFF} versus V_{CC}

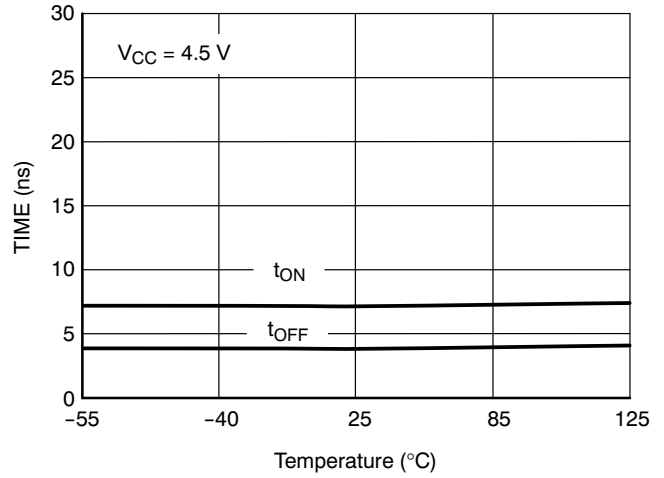


Figure 15. t_{ON} and t_{OFF} versus Temp

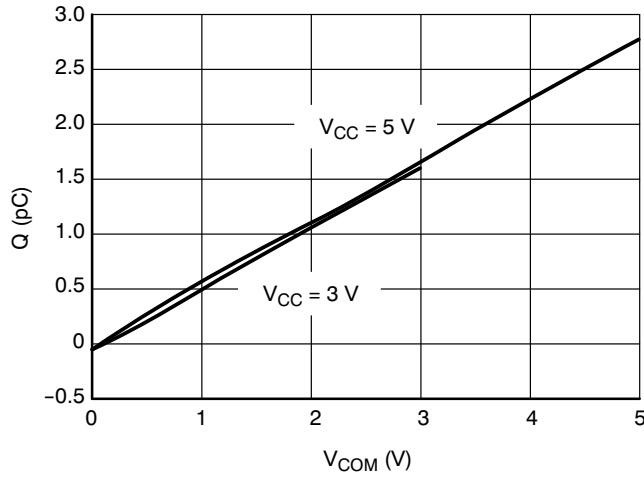


Figure 16. Charge Injection versus COM Voltage

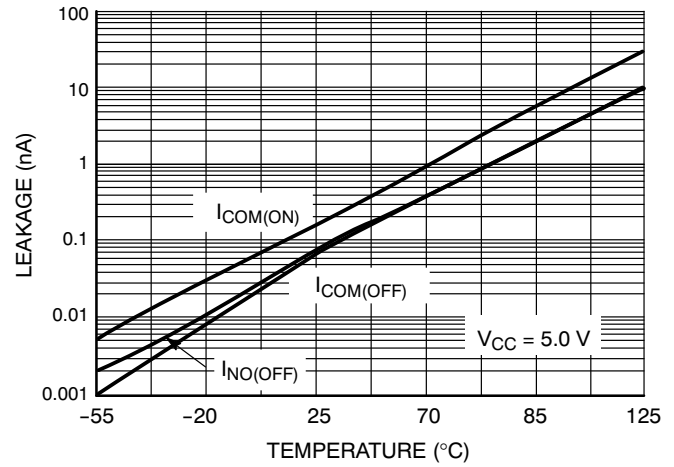


Figure 17. Switch Leakage versus Temperature

NLAST4053

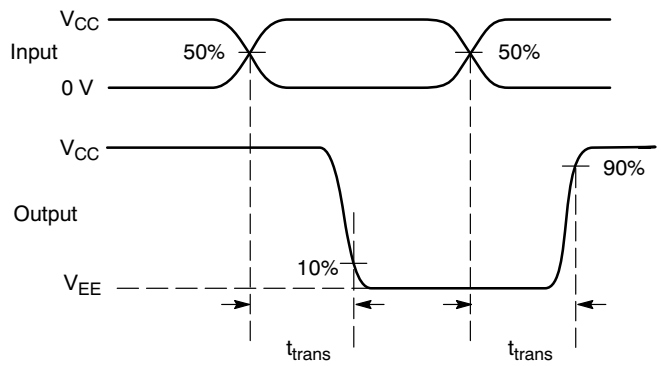
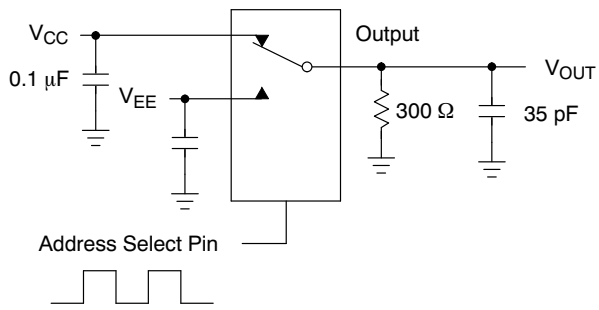


Figure 18. Channel Selection Propagation Delay

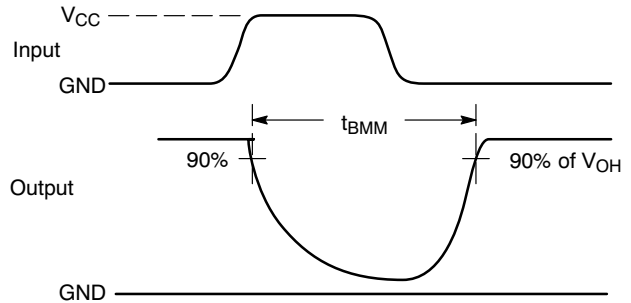
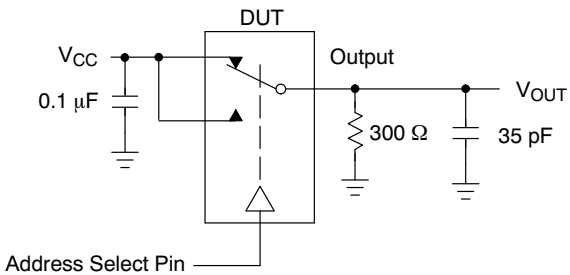


Figure 19. t_{BMM} (Time Break-Before-Make)

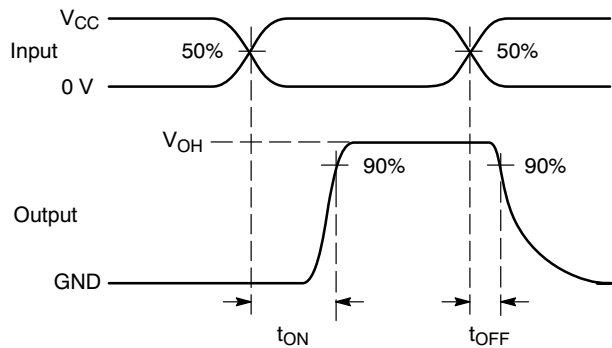
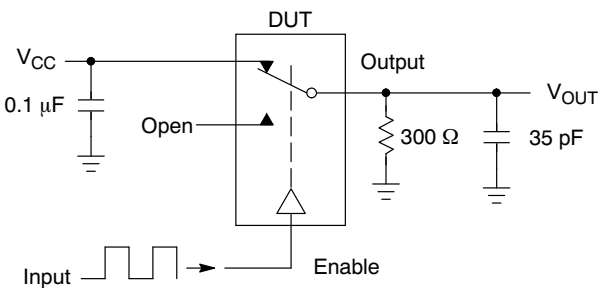


Figure 20. $t_{\text{ON}}/t_{\text{OFF}}$

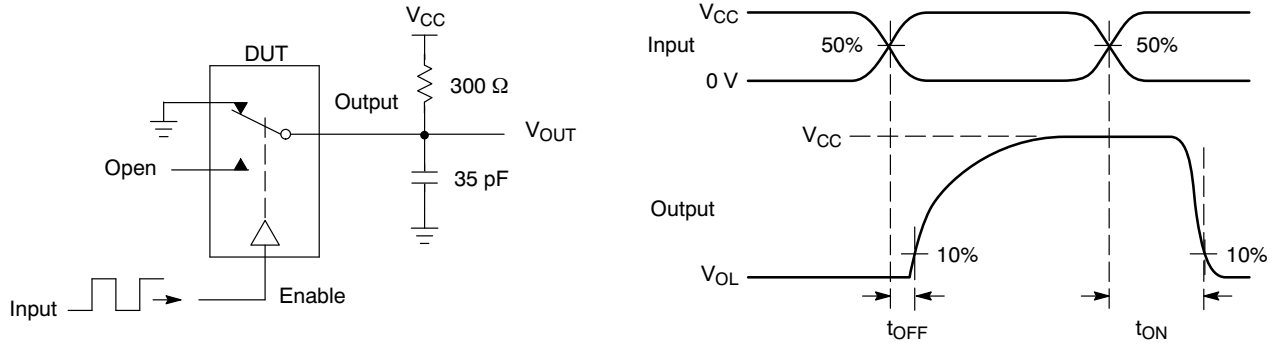
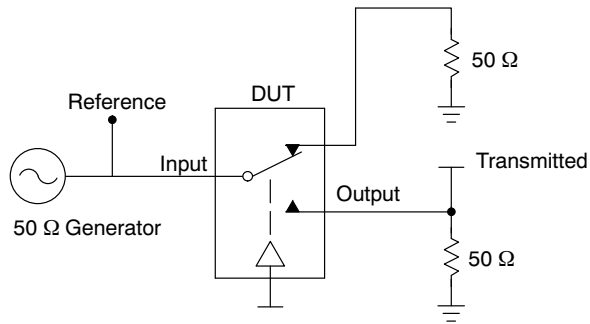


Figure 21. t_{ON}/t_{OFF}



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch. V_{ISO} , Bandwidth and V_{ONL} are independent of the input signal direction.

$$V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log} \left(\frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz}$$

$$V_{ONL} = \text{On Channel Loss} = 20 \text{ Log} \left(\frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz to } 50 \text{ MHz}$$

Bandwidth (BW) = the frequency 3 dB below V_{ONL}

Figure 22. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/ V_{ONL}

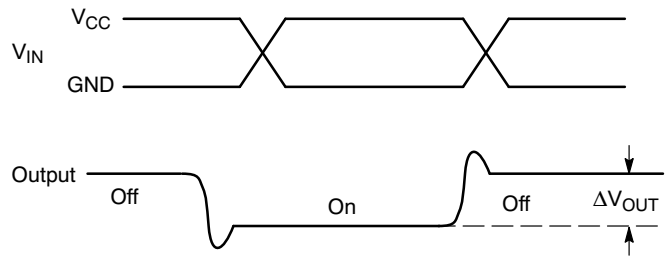
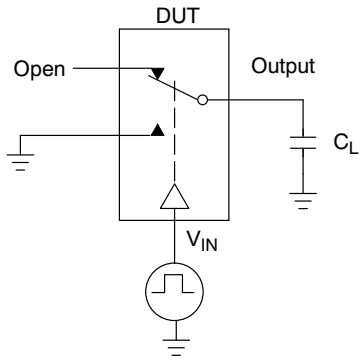


Figure 23. Charge Injection: (Q)

TYPICAL OPERATION

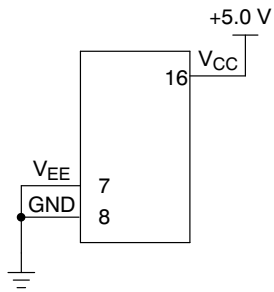


Figure 24. 5.0 Volts Single Supply
 $V_{CC} = 5.0\text{ V}$, $V_{EE} = 0$

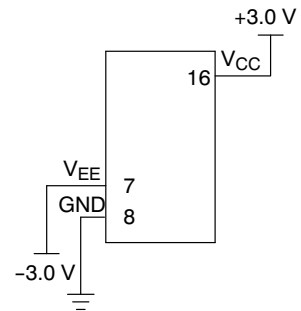
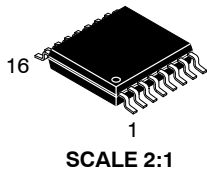


Figure 25. Dual Supply
 $V_{CC} = 3.0\text{ V}$, $V_{EE} = -3.0\text{ V}$

MECHANICAL CASE OUTLINE

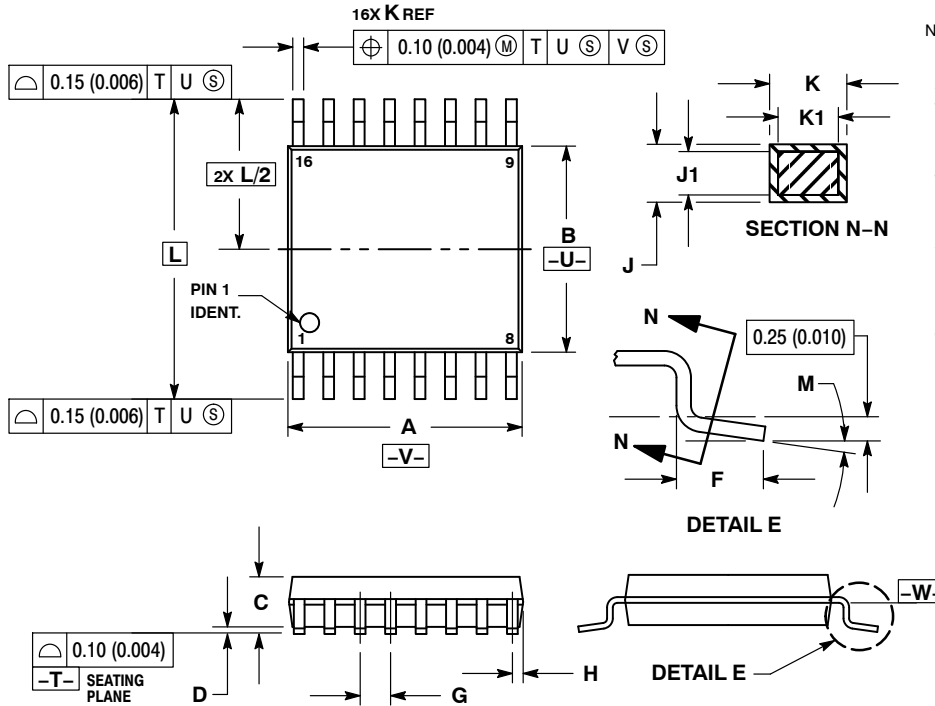
PACKAGE DIMENSIONS

ON Semiconductor®



TSSOP-16
CASE 948F-01
ISSUE B

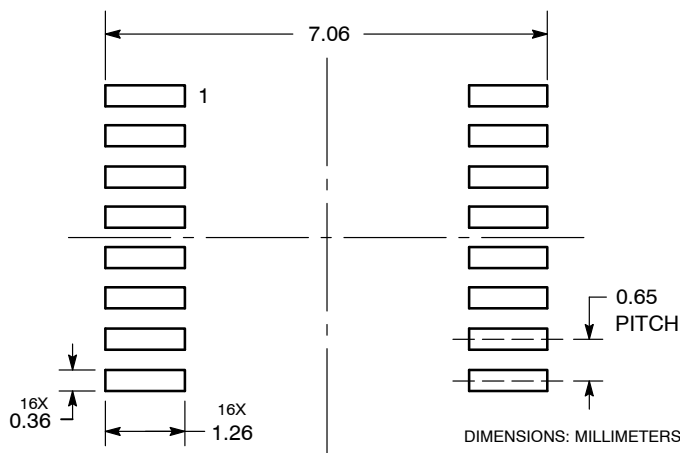
DATE 19 OCT 2006



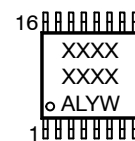
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

DOCUMENT NUMBER:	98ASH70247A	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	TSSOP-16	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:
Voice Mail: 1 800-282-9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative